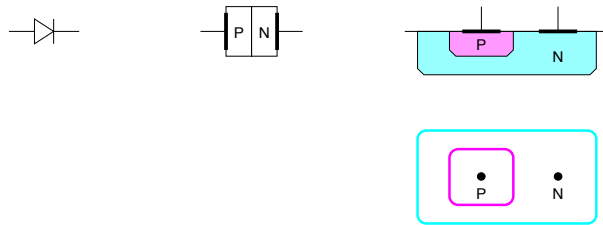


## Components for Digital IC Design

### Diodes and Bipolar Transistors

Diode



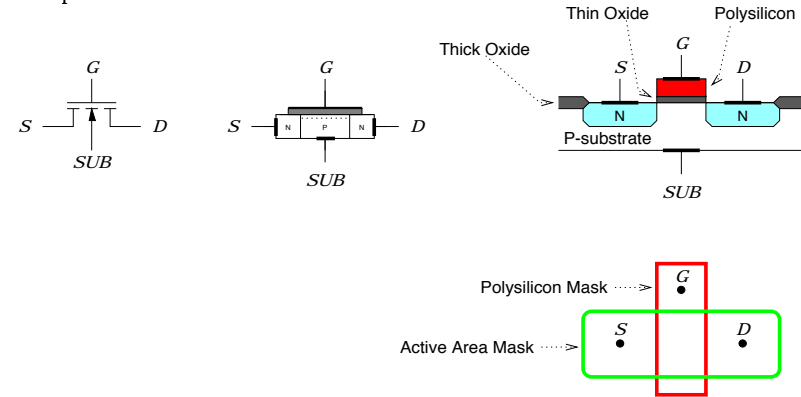
- Ideal structure - 1D
- Real structure - 3D
- Depth controlled implants.

3001

## Components for Digital IC Design

### MOS Transistors

Simple NMOS Transistor

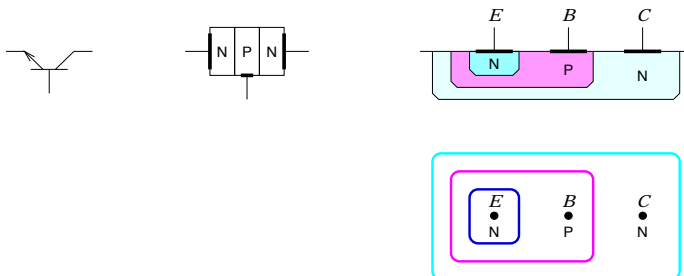


3003

## Components for Digital IC Design

### Diodes and Bipolar Transistors

NPN Transistor



- Two n-type implants.

3002

## Components for Digital IC Design

### Simple NMOS Transistor

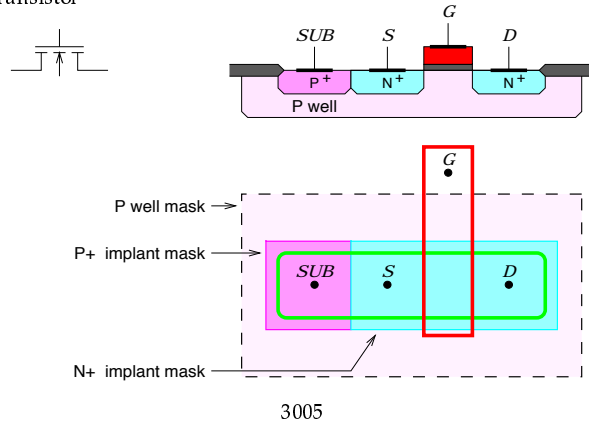
- Active Area mask defines extent of *Thick Oxide*.
- Polysilicon mask also controls extent of *Thin Oxide* (alias *Gate Oxide*).
- N-type implant has no extra mask.
  - It is blocked by thick oxide and by polysilicon.
  - The implant is *Self Aligned*.
- Substrate connection is to bottom of wafer.
  - All substrates to ground.
- Gate connection not above transistor area.
  - Design Rule.

3004

## Components for Digital IC Design

### MOS Transistors

NMOS Transistor



## Components for Digital IC Design

### NMOS Transistor

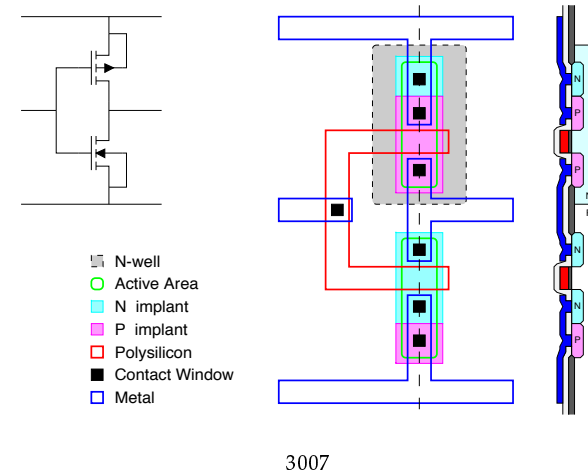
Where it is not suitable for substrate connections to be shared, a more complex process is used.

- Five masks must be used to define the transistor:
  - P Well
  - Active Area
  - Polysilicon
  - N+ implant
  - P+ implant
- P Well, for isolation.
- Top *substrate* connection.
- P+/N+ implants produce good *ohmic* contacts.

3006

## CMOS Process

### CMOS Inverter

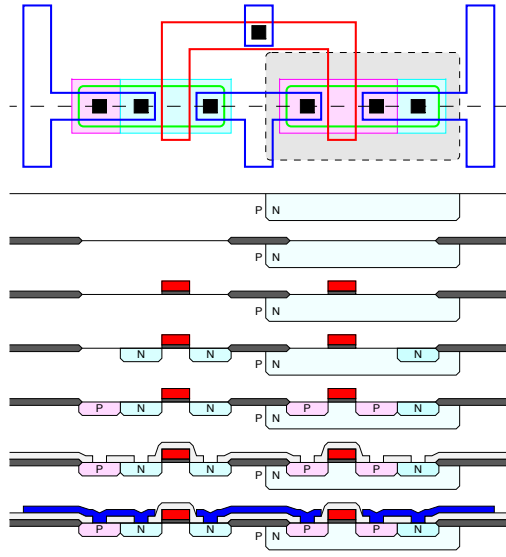
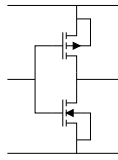


## CMOS Process

### CMOS Inverter

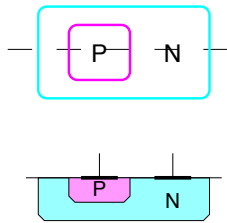
- The process described here is an *N Well process* since it has only an N Well. P Well and Twin Tub processes also exist.
- Note that the P-N junction between chip substrate and N Well will remain reverse biased. Thus the transistors remain isolated.
- N implant defines NMOS source/drain and PMOS substrate contact.
- P implant defines PMOS source/drain and NMOS substrate contact.

3008

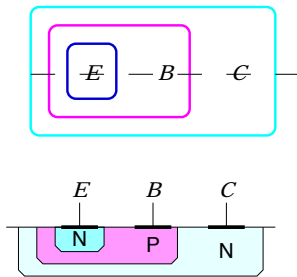


- N-well
- Active Area  
defines Thick Oxide
- Polysilicon  
defines Thin Oxide
- N implant  
aligned to AA and Poly
- P implant  
aligned to AA and Poly
- Contact Window
- Metal

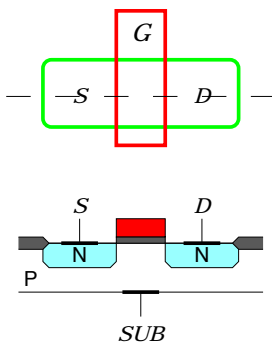
Diode



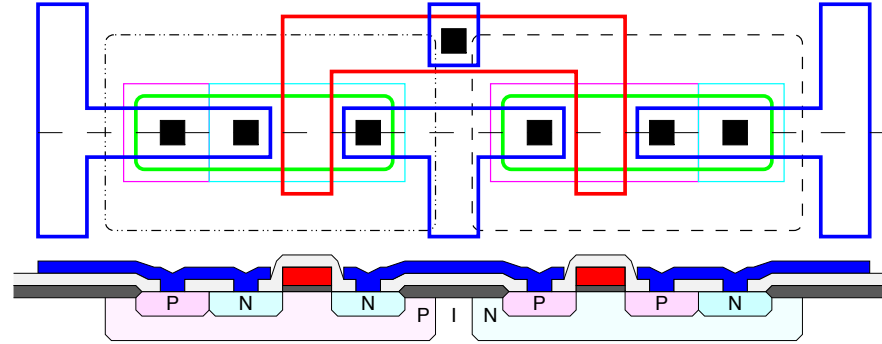
NPN Transistor



NMOS Enhancement transistor  
NMOS Process



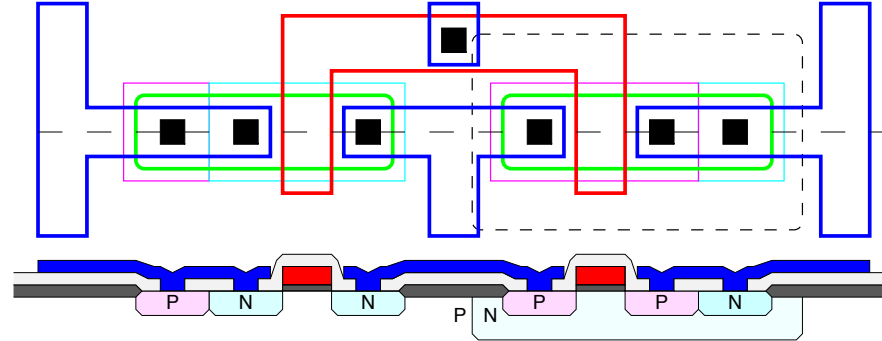
CMOS Inverter



Twin Tub CMOS Process

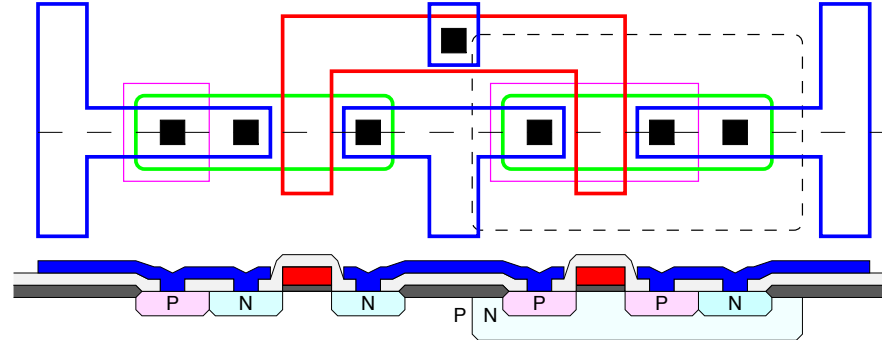
CMOS Inverter

N-Well CMOS Process (with explicit N+ implant mask)



CMOS Inverter

N-Well CMOS Process (without explicit N+ implant mask)



Features may be determined by a number of masks  
e.g. NMOS source drain: ActiveArea AND NOT(NWell OR Poly OR PImplant)